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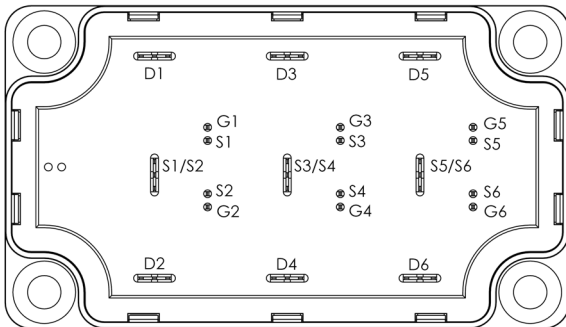
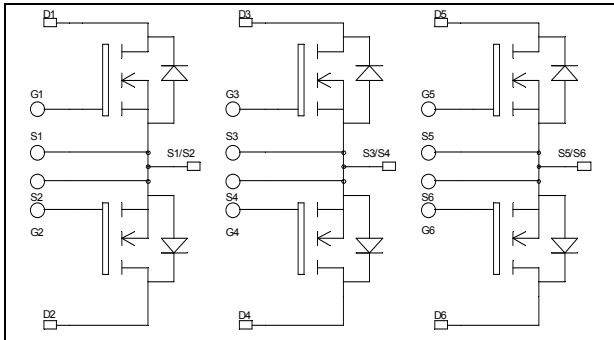
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## Triple dual common source MOSFET Power Module

$V_{DSS} = 100V$   
 $R_{DSon} = 9m\Omega \text{ typ @ } T_j = 25^\circ C$   
 $I_D = 139A \text{ @ } T_c = 25^\circ C$



### Application

- AC Switches
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

### Features


- Power MOS V<sup>®</sup> MOSFETs
  - Low  $R_{DSon}$
  - Low input and Miller capacitance
  - Low gate charge
  - Avalanche energy rated
  - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
  - Symmetrical design
  - Lead frames for power connections
- High level of integration

### Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Very low (12mm) profile
- Each leg can be easily paralleled to achieve a dual common source configuration of three times the current capability
- RoHS Compliant

### Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
$V_{DSS}$	Drain - Source Breakdown Voltage	100	V
$I_D$	Continuous Drain Current	$T_c = 25^\circ C$	139
		$T_c = 80^\circ C$	100
$I_{DM}$	Pulsed Drain current	430	
$V_{GS}$	Gate - Source Voltage	$\pm 30$	V
$R_{DSon}$	Drain - Source ON Resistance	10	$m\Omega$
$P_D$	Maximum Power Dissipation	$T_c = 25^\circ C$	390
$I_{AR}$	Avalanche current (repetitive and non repetitive)	100	A
$E_{AR}$	Repetitive Avalanche Energy	50	mJ
$E_{AS}$	Single Pulse Avalanche Energy	3000	


**CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)

All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

**Electrical Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 100V$			100	$\mu\text{A}$
		$V_{GS} = 0V, V_{DS} = 80V$			500	
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10V, I_D = 69.5A$		9	10	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 2.5\text{mA}$	2		4	V
$I_{GSS}$	Gate – Source Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$			$\pm 100$	nA

**Dynamic Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$C_{iss}$	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1\text{MHz}$		9875		pF
$C_{oss}$	Output Capacitance			3940		
$C_{rss}$	Reverse Transfer Capacitance			1470		
$Q_g$	Total gate Charge	$V_{GS} = 10V$ $V_{Bus} = 50V$ $I_D = 139A$		350		nC
$Q_{gs}$	Gate – Source Charge			60		
$Q_{gd}$	Gate – Drain Charge			180		
$T_{d(on)}$	Turn-on Delay Time	<b>Inductive switching @ <math>125^\circ\text{C}</math></b> $V_{GS} = 15V$ $V_{Bus} = 66V$ $I_D = 139A$ $R_G = 5\Omega$		35		ns
$T_r$	Rise Time			70		
$T_{d(off)}$	Turn-off Delay Time			95		
$T_f$	Fall Time			125		
$E_{on}$	Turn-on Switching Energy	<b>Inductive switching @ <math>25^\circ\text{C}</math></b> $V_{GS} = 15V, V_{Bus} = 66V$ $I_D = 139A, R_G = 5\Omega$		552		$\mu\text{J}$
$E_{off}$	Turn-off Switching Energy			604		
$E_{on}$	Turn-on Switching Energy	<b>Inductive switching @ <math>125^\circ\text{C}</math></b> $V_{GS} = 15V, V_{Bus} = 66V$ $I_D = 139A, R_G = 5\Omega$		608		$\mu\text{J}$
$E_{off}$	Turn-off Switching Energy			641		

**Source - Drain diode ratings and characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$I_S$	Continuous Source current (Body diode)	$T_c = 25^\circ\text{C}$			139	A
		$T_c = 80^\circ\text{C}$			100	
$V_{SD}$	Diode Forward Voltage	$V_{GS} = 0V, I_S = -139A$			1.3	V
dv/dt	Peak Diode Recovery ①				5	V/ns
$t_{rr}$	Reverse Recovery Time	$I_S = -139A$ $V_R = 66V$			270	ns
$Q_{rr}$	Reverse Recovery Charge	$di/dt = 100A/\mu\text{s}$			2.9	$\mu\text{C}$

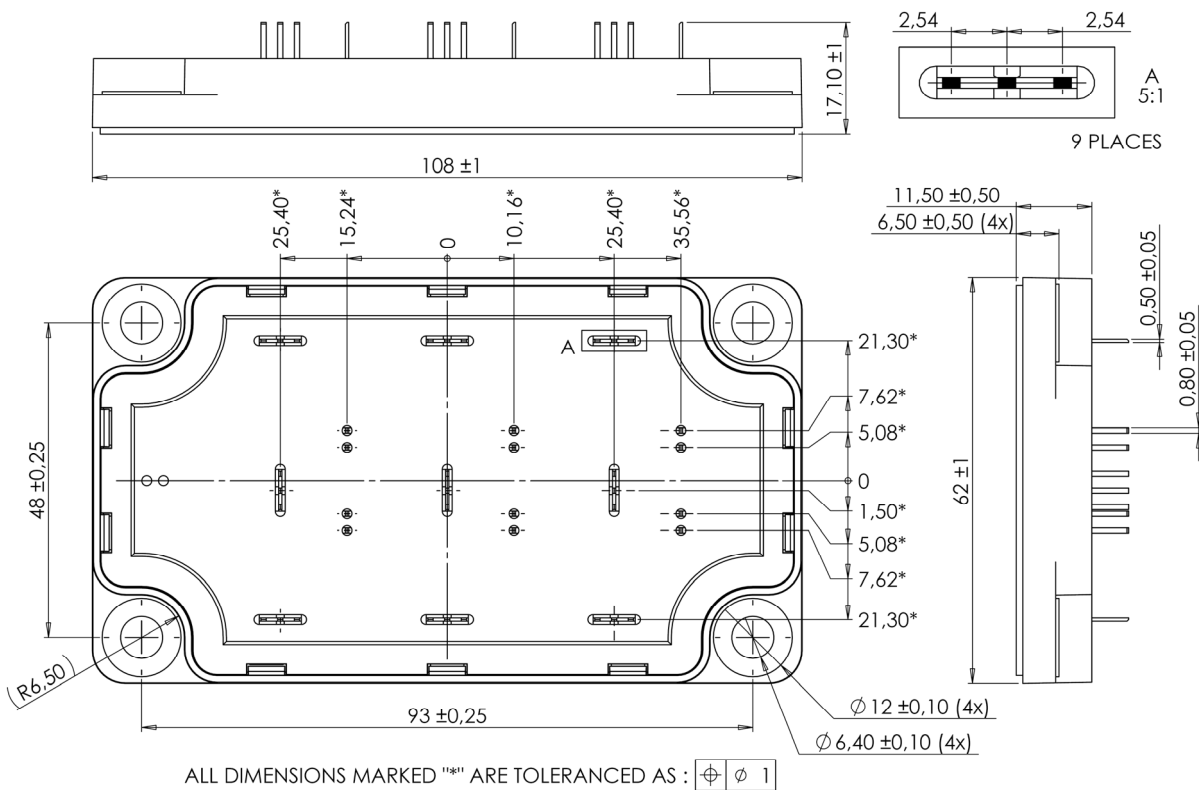
① dv/dt numbers reflect the limitations of the circuit rather than the device itself.

$$I_S \leq -139A \quad di/dt \leq 700A/\mu\text{s} \quad V_R \leq V_{DSS} \quad T_j \leq 150^\circ\text{C}$$

## Thermal and package characteristics

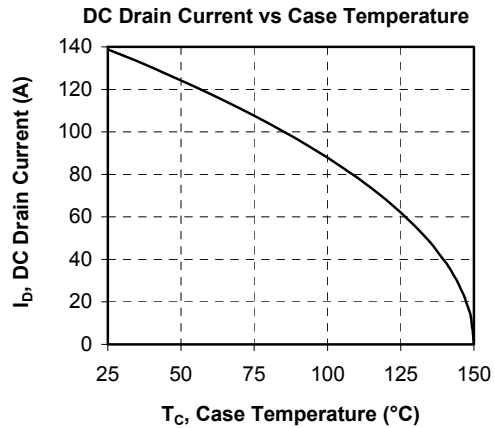
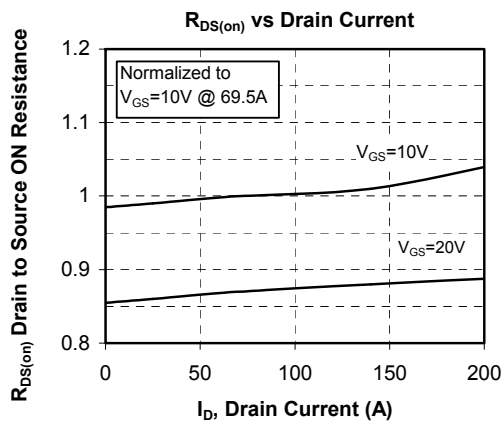
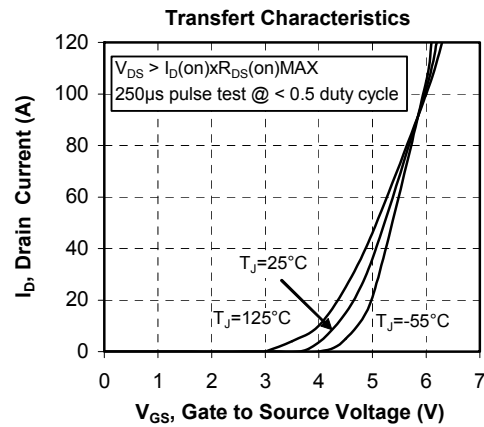
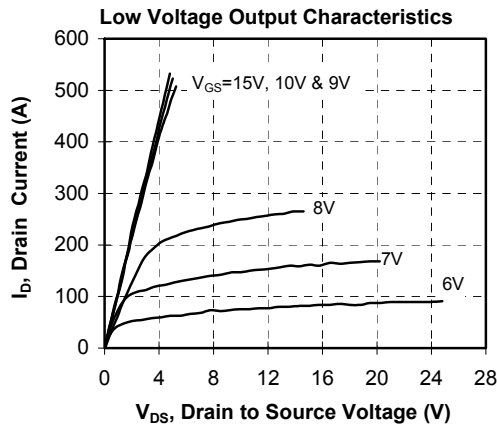
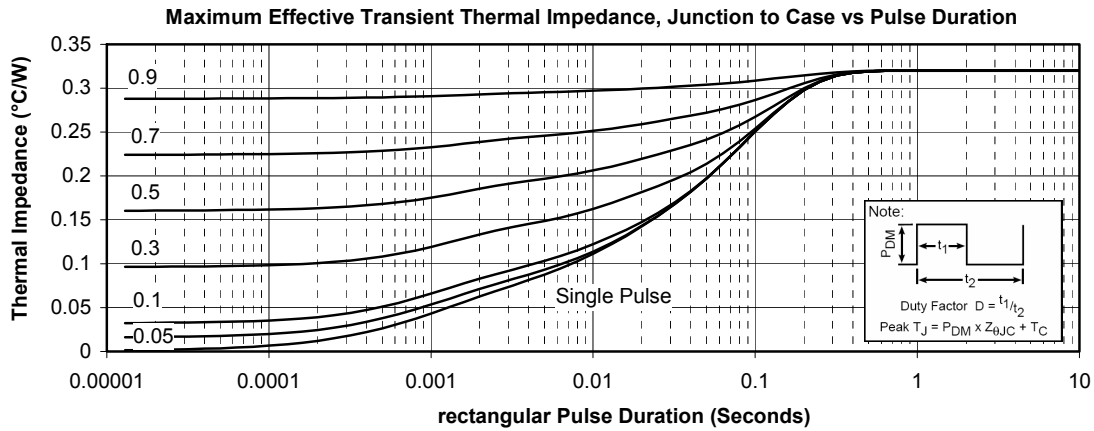
Symbol	Characteristic	Min	Typ	Max	Unit	
R <sub>thJC</sub>	Junction to Case Thermal Resistance			0.32	°C/W	
V <sub>ISOL</sub>	RMS Isolation Voltage, any terminal to case t=1 min, 50/60Hz	4000			V	
T <sub>J</sub>	Operating junction temperature range	-40		150	°C	
T <sub>STG</sub>	Storage Temperature Range	-40		125		
T <sub>C</sub>	Operating Case Temperature	-40		100		
Torque	Mounting torque	To heatsink	M6	3	5	N.m
Wt	Package Weight				250	g

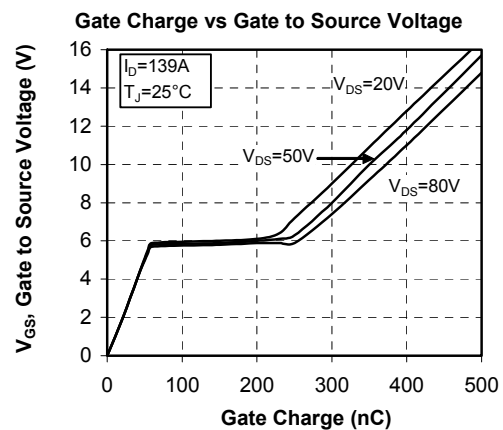
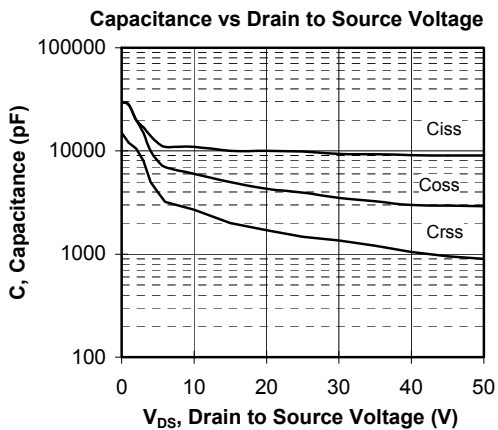
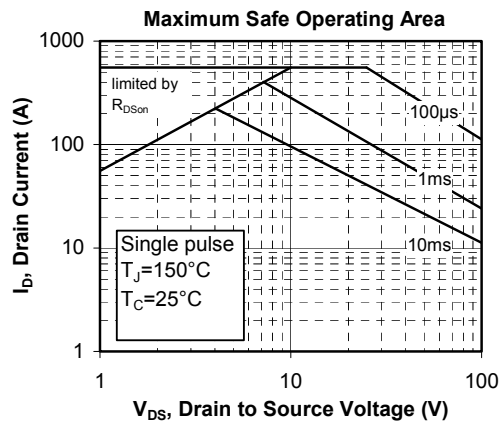
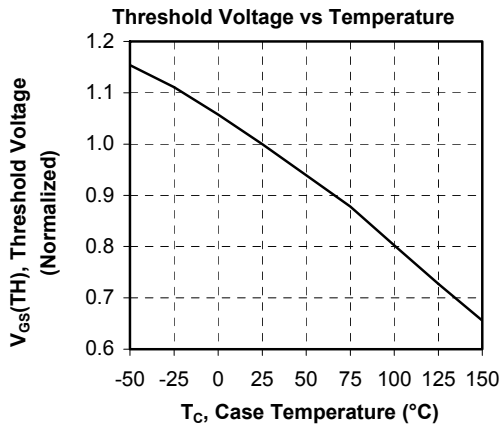
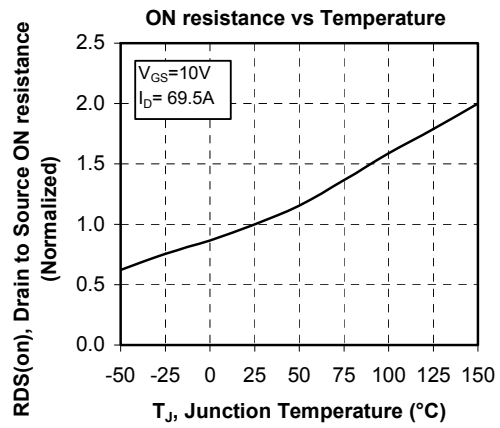
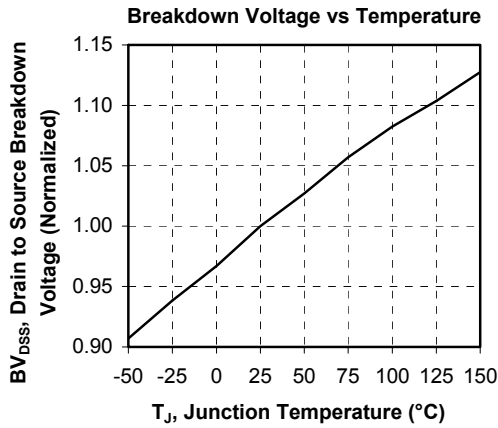
## SP6-P Package outline (dimensions in mm)



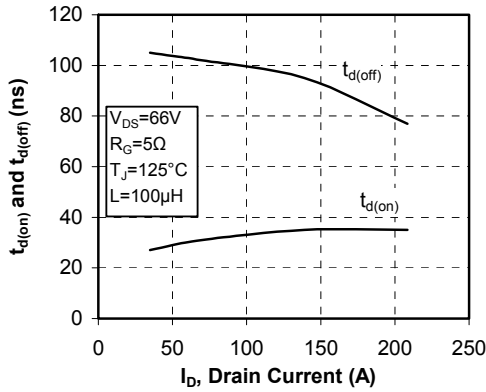
See application note 1902 - Mounting Instructions for SP6-P (12mm) Power Modules on [www.microsemi.com](http://www.microsemi.com)

## Typical Performance Curve

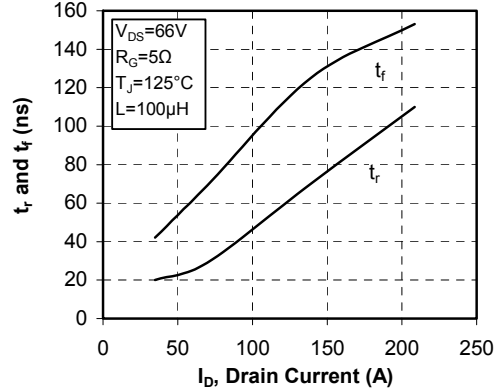




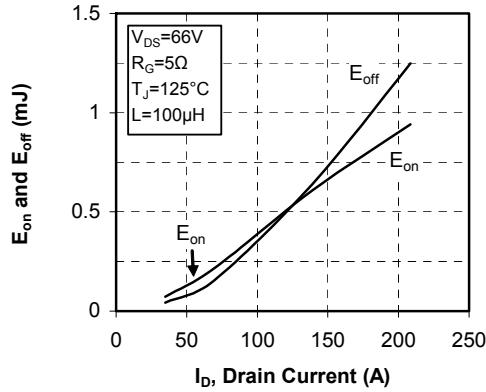
**Delay Times vs Current**



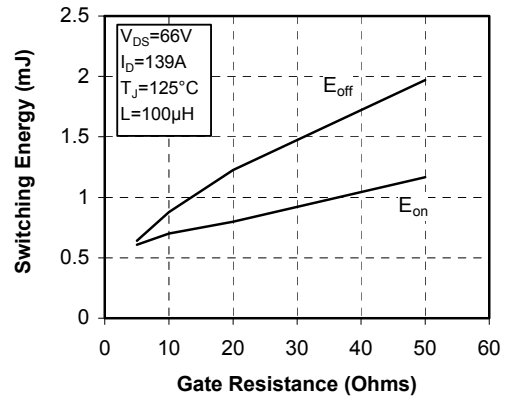
**Rise and Fall times vs Current**



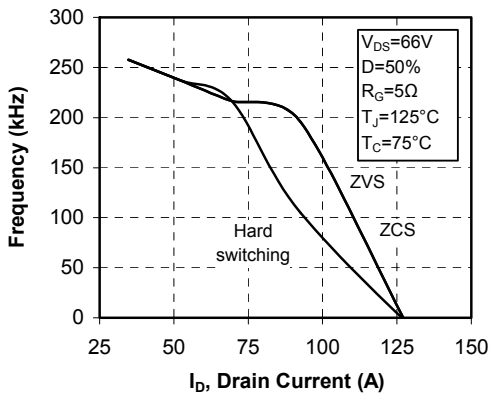
**Switching Energy vs Current**



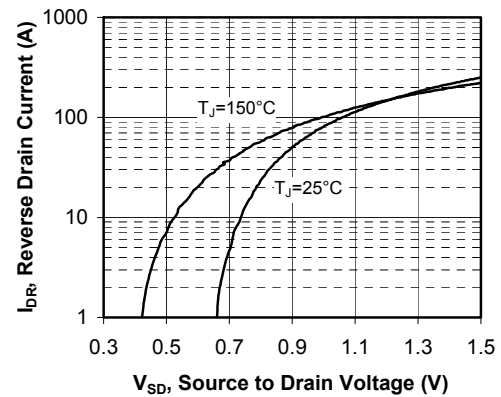
**Switching Energy vs Gate Resistance**



**Operating Frequency vs Drain Current**



**Source to Drain Diode Forward Voltage**



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